

Amendments to Specification

In the paragraph on page 13, line 27, to page 14, line 2 of the specification please make the following changes.

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--As shown in Figure 3D, the leads 22B also include an outer layer ~~46A~~ 46B, which comprises a material selected to provide a non-bonding surface for the bumped contacts 16. For example, for bumped contacts 16 formed of solder, the outer layer ~~46A~~ 46B can comprise a metal that is not solder wettable. Suitable metals include Ti, $TiSi_2$ and Al. Rather than metal, the outer layer ~~46A~~ 46B, can comprise a conductive polymer selected to provide a non-bonding surface. Suitable conductive polymers include carbon films and metal filled silicone.--

In the paragraph on page 19, lines 4-9, of the specification please make the following changes.

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--Next, as shown in Figure 7B, blades 28B are formed also as previously described. In addition, the non-bonding outer layer ~~46A~~ 46B can be formed on the metal layer 54B using a suitable deposition process such as CVD, electrodeposition deposition, or electroless deposition of a metal or conductive polymer layer.--